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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









December 2008

SG6510X1 — PC Power Supply Supervisors

Features

- Over-Voltage Protection (OVP) for 3.3V, 5V, 12V
- Under-Voltage Sense (UVS) and Under-Voltage Protection (UVP) for 3.3V, 5V
- Open-Drain Output for PGO and FPO Pins
- 300ms Power-Good Delay
- 75ms Turn-on Delay for 3.3V and 5V
- 2.8ms PSON Control to FPO Turn-off Delay
- 38ms /38ms PSON Control Debounce
- 350µs Width Noise Deglitches
- 2ms UVP Debounce Time
- 1ms UVS Debounce Time
- No Lockup During the Fast AC Power On/Off
- Brownout Protection Function for 3.3V and 5V
- Wide Supply Voltage Range from 4V to 15V

Description

SG6510 is designed to provide the voltage supervisor function, remote on/off PSON function, power-good (PGO) indicator function, and fault protection (FPO) function for switching power systems.

For the supervisor function, it provides the over-voltage protection (OVP) monitoring for 3.3V, 5V, and 12V (12V via VDD pin); under-voltage sense (UVS) monitoring for 3.3V and 5V; and under-voltage protection (UVP) monitoring for 3.3V and 5V. When 3.3V or 5V voltage is decreasing to 2.8V and 4.2V, respectively, the undervoltage sense (UVS) function is enabled to reset the PGO signal from high to low. If 3.3V or 5V voltage is further decreasing to 2.5V and 3.6V, respectively, FPO is set high to turn off the PWM controller IC. To achieve better immunity for lighting surge glitch and to prevent accidental power shut down during dynamic loading condition, the debounce time for UVP and UVS is 2ms/1ms, respectively. The deglitch time for OVP is 75µs for better noise immunity. During an AC sag or brownout situation, UVP functions can still be enabled to protect power supply in case of output short circuit.

The power supply is turned on after 38ms debounce time when the PSON signal is set from high to low. To turn off the power supply, the PSON signal is set from low to high and the debounce time is 38ms. The PGI circuitry provides a sufficient power-down warning signal for PGO. When PGI input is lower than the internal 1.2V reference voltage, after 350µs debounce time, the PGO signal is pulled low.

Ordering Information

Part Number	Operating Temperature Range	Package	© Eco Status	Packing Method
SG6510DY1	-40°C to +125°C	DIP-8	Green	Tube
SG6510DZ1	-40°C to +125°C	DIP-8	RoHS	Tube
SG6510SZ1	-40°C to +125°C	SOP-8	RoHS	Tape & Reel
SG6510SY1	-40°C to +125°C	SOP-8	Green	Tape & Reel

For Fairchild's definition of "green" please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.

Application Diagram

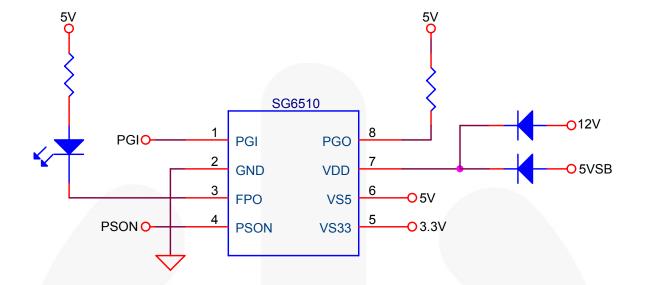


Figure 1. Typical Application

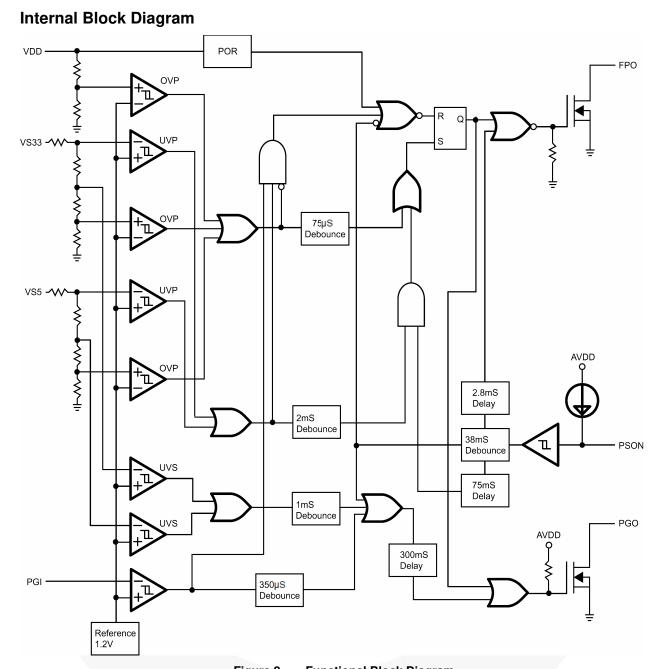
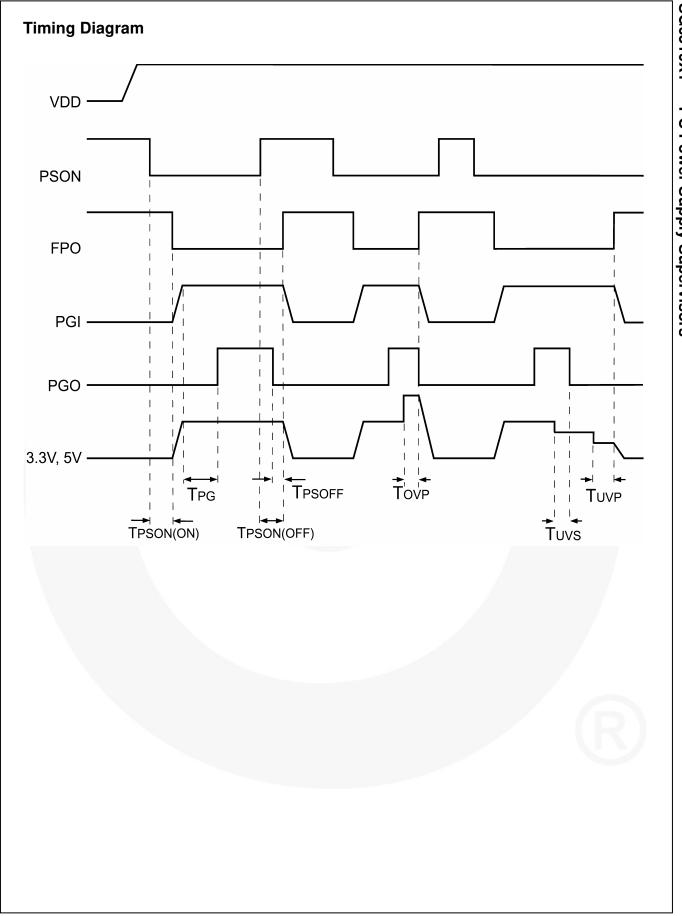
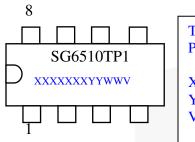


Figure 2. Functional Block Diagram

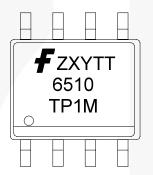


Marking Information



T: D = DIP
P: Z = Lead Free
Null = regular package
XXXXXXX: Wafer Lot
YY: Year; WW: Week
V: Assembly Location

** Marking for SG6510DZ1 (Pb-free) SG6510SZ1 (Pb-free)



1'st line

Z: Assembly plant code

X: Year code

Y: Week code

TT: Die run code

3'rd line

T: Package type (D = DIP, S=SOP)

P: Y=Green package

M: Manufacture flow code

Marking for SG6510DY1 (Green-compound) SG6510SY1 (Green-compound)

Figure 3. Top Mark

Pin Configurations

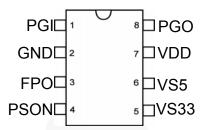


Figure 4. Pin Configuration

Pin Definitions

Pin #	Name	Туре	Description
1	PGI	Analog Input	Power-good input. For ATX SMPS, it detects main AC voltage undervoltage and/or failure.
2	GND	Supply	Ground.
3	FPO	Logic Output	Fault protection output (invert). Output signal to control the PWM IC. For example, it controls the PWM IC of primary side through an optocoupler. When FPO is low, the main SMPS is operational.
4	PSON	Logic Input	Remote on/off logic input from CPU or main-board. Turn on/off the PWM output after a 38ms delay.
5	VS33	Analog Input	3.3 V over/under-voltage control sense input.
6	VS5	Analog Input	5 V over/under-voltage control sense input.
7	VDD	Supply	Supply voltage; 4V ~ 15V. For ATX SMPS, it is connected to 5V-standby and 12V through diodes, respectively.
8	PGO	Logic Output	Power-good logic output, 0 or 1(open-drain). Power good = 1 means that the power is good for operation. The power-good delay is 300ms.

Function Table

PGI	PSON	UV Sense (3.3V or 5V)	UV Protection (3.3V or 5V)	OV Protection	FPO	PGO
PGI<1.2V	L	No	No	No	L	L
PGI<1.2V	L	Yes	No	No	L	L
PGI<1.2V	L	No	Yes	No	L	L
PGI<1.2V	L	No	No	Yes	Н	L
PGI<1.2V	L	Yes	Yes	No	L	L
PGI<1.2V	L	Yes	No	Yes	Н	L
PGI<1.2V	L	No	Yes	Yes	Н	L
PGI<1.2V	L	Yes	Yes	Yes	Н	L
PGI>1.2V	L	No	No	No	L	Н
PGI>1.2V	L	Yes	No	No	L	L
PGI>1.2V	L	No	Yes	No	Н	L
PGI>1.2V	L	No	No	Yes	Н	L
PGI>1.2V	L	Yes	Yes	No	Н	L
PGI>1.2V	L	Yes	No	Yes	Н	L
PGI>1.2V	/L	No	Yes	Yes	Н	L
PGI>1.2V	/(L	Yes	Yes	Yes	Н	L
Х	Н	Х	Х	Х	Н	L

X = Don't care

FPO = L means: fault IS NOT latched FPO = H means: fault IS latched

PGO = L means: fault
PGO = H means: No fault

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit	
V_{DD}	DC Supply Voltage		-0.3	16	V
Vi	Input Voltage	PSON, VS33, VS5, PGI	-0.3	8.0	V
Vout	Output Voltage	FPO	-0.3	16	٧
V 001	Output voltage	PGO	-0.3	8.0	V
TA	Operating Free Air Temperature Range		-40	+85	°C
T _{STG}	Storage Temperature Range		-55	+150	°C
TL	Soldering Temperature			+260	°C
ESD	Electrostatic Discharge Capability	Human Body Model		2	KV

Note:

1. Stresses above those listed may cause permanent damage to the device.

Recommended Operating Conditions

Symbol	Parameter		Min.	Max.	Unit
V_{DD}	DC Supply Voltage		4	15	V
V_{IL}	Input Voltage	PSON, VS33, VS5, PGI		7	V
W	Output Voltage	FPO		15	· V
V _{OUT}	Output Voltage	PGO		7	
1	Output Sink Current	FPO		20	
I _o SINK	Output Sink Current	PGO		10	mA
T _R	Supply Voltage Rising Time ⁽²⁾		1		ms
T _A	Operating Free Air Temperature Range		-30	85	°C

Note:

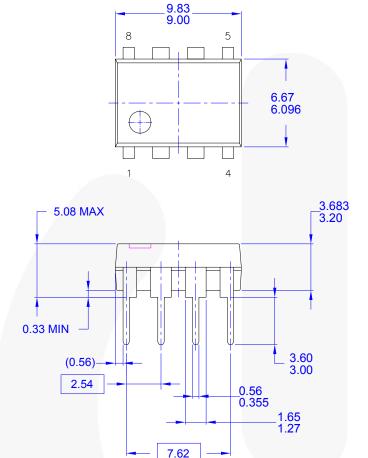
2. V_{DD} rising and falling slew rate must be less than 14V/ms.

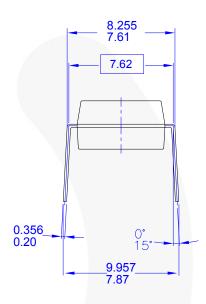
Electrical Characteristics

Unless otherwise noted, V_{DD} =12V and T_A =25°C.

Symbol	Parameter Conditions		Min.	Тур.	Max.	Units
Over-Vol	tage Protection					
	Over-Voltage Protection VS33		3.7	3.9	4.1	
V_{OVP}	Over-Voltage Protection VS5		5.7	6.1	6.5	V
	Over-Voltage Protection V _{DD}		13.2	13.8	14.4	
I _{LKG}	Leakage Current (FPO)	V _{FPO} = 5V			5	μΑ
V _{OL}	Low-Level Output Voltage (FPO)	I _{sink} 20mA			0.7	V
t _{D-VDDOVP}	Timing, OVP to Protection		33	75	110	ms
Under-Vo	oltage and PGI, PGO					
V_{PGI}	Input Threshold Voltage PGI		1.15	1.20	1.25	V
\/	Under-Voltage Sense VS33		2.6	2.8	3.0	V
V _{UVS}	Under-Voltage Sense VS5		4.0	4.2	4.4	1 V
\/	Under-Voltage Protection VS33		2.3	2.5	2.7	V
V_{UVP}	Under-Voltage Protection VS5		3.4	3.6	3.8	
tuvs	Timing UVS to Sense (PG)		0.6	1.0	1.5	ms
t _{UVP}	Timing UVP to Protection (FPO)		1.3	2.0	3.0	ms
I _{LKG}	Leakage Current (PGO)	PGO = 5V			5	μA
V_{OL}	Low-Level Output Voltage (PGO)	V_{DD} = 12V, I_{SINK} 10mA			0.7	V
t _{UVE}	Under-Voltage Enable Delay Time		49	75	114	ms
t	Timing PG Delay	PGI to PGO	200	300	450	ms
t _{PG}	Noise Deglitch Time	PGI to PGO	200	350	450	μs
PSON Co	ontrol					
I _{PSON}	Input Pull-up Current	PSON = 0V	100	160	220	μΑ
V_{IH}	High-Level Input Voltage		2.40	1.85		V
V_{IL}	Low-Level Input Voltage			1.35	1.2	V
	Timing DOON to On/Off	On	24	38	57	
tpson	Timing, PSON to On/Off	Off	24	38	57	ms
t _{PSOFF}	Timing PG Low to Power Off		1.6	2.8	4.5	ms
Total Dev	vice					
I _{DD}	Supply Current	PSON = 5V/V _{DD} = 5V		0.7	1.5	mA

Physical Dimensions





NOTES: UNLESS OTHERWISE SPECIFIED

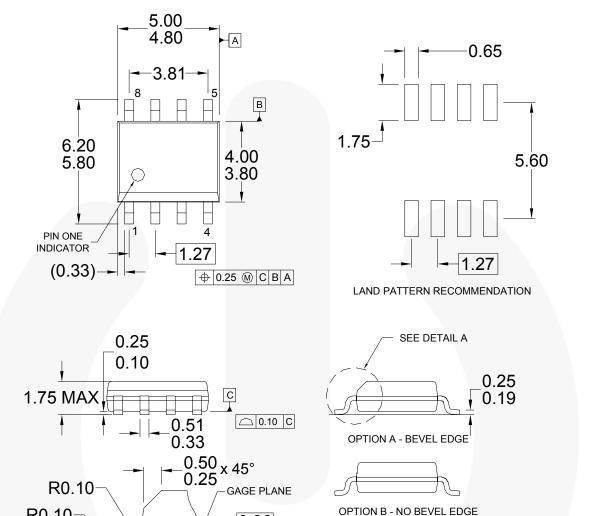
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- E) DRAWING FILENAME AND REVSION: MKT-N08FREV2.

Figure 5. 8-Pin, DIP-8 Package

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- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD **FLASH OR BURRS**
- D) LANDPATTERN STANDARD: SOIC127P600X175-8M.
- E) DRAWING FILENAME: M08AREV13

Figure 6. 8-Pin SOP Package

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SEATING PLANE

(1.04)

DETAIL A

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